High-Speed CAN Transceiver with Signal Improvement Capability (SIC) and Standby Mode

UMCAN1462VS8 ***SOP8***
UMCAN1462NS8 ***SOP8***
UMCAN1462VDA ***DFN8 3.0×3.0***
UMCAN1462NDA ***DFN8 3.0×3.0***

1 Description

The UMCAN1462 is a high-speed CAN transceiver that provides an interface between a Controller Area Network (CAN) protocol controller and the physical two-wire CAN bus. The transceiver is designed for high-speed CAN applications in the automotive industry, providing the differential transmit and receive capability to (a microcontroller with) a CAN protocol controller.

The UMCAN1462 offers a feature set optimized for 12 V automotive applications and excellent ElectroMagnetic Compatibility (EMC) performance. Additionally, the UMCAN1462 features:

- Ideal passive behavior to the CAN bus when the supply voltage is off
- A very low–current Standby mode with bus wake–up capability
- Excellent EMC performance, even without a common mode choke
- Variants with a V_{IO} pin can be interfaced directly with microcontrollers with supply voltages from 3.3 V and 5 V

The UMCAN1462 transceiver implements the CAN physical layer as defined in ISO 11898-2:2024 third edition and SAE J2284-1 to SAE J2284-5, and is fully interoperable with high-speed Classical CAN and CAN FD transceivers. The UMCAN1462 includes CAN signal improvement capability (SIC), as defined in ISO 11898-2:2024 parameter set C. CAN signal improvement significantly reduces signal ringing in a network, allowing reliable CAN FD communication to function in larger topologies. In addition, the UMCAN1462 features a much tighter bit timing symmetry performance to enable CAN FD communication up to 8 Mbit/s. These features make the UMCAN1462 an excellent choice for all types of HS-CAN networks, in nodes that require a standby mode with wake-up capability via the bus.

2 Applications

- High-speed CAN applications in the automotive industry
- Infrastructure and farm equipment
- Elevator
- Networked sensors/actuators

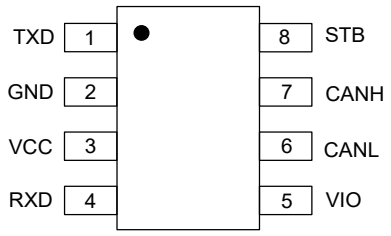
3 Features

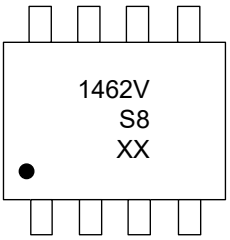
- Fully ISO 11898-2:2024, SAE J2284-1 to SAE J2284-5 and SAE J1939-14 compliant
- Supply Voltage: 4.5V to 5.5V
- V_{IO} Level shifting supports 2.9V to 5.5V
- Signal Improvement Capability (SIC)
- Very low-current Standby mode with local and bus wake-up capability
- Optimized for use in 12 V automotive systems
- Low Electromagnetic Emission (EME) and high Electromagnetic Immunity (EMI), according to proposed EMC Standards IEC 62228-3 and SAE J2962-2
- Up to 8 Mbps data rates

4 Ordering Information

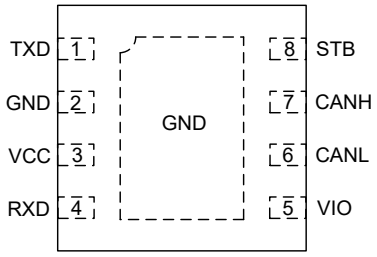
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UMCAN1462VS8	1462VS8	SOP8	3000pcs/13Inch Tape & Reel
UMCAN1462VDA	1462V	DFN8 3.0×3.0	3000pcs/13Inch Tape & Reel
UMCAN1462NS8	1462NS8	SOP8	3000pcs/13Inch Tape & Reel
UMCAN1462NDA	1462N	DFN8 3.0×3.0	3000pcs/13Inch Tape & Reel

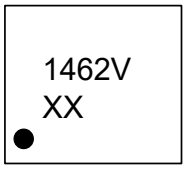
5 Pin Configuration and Function



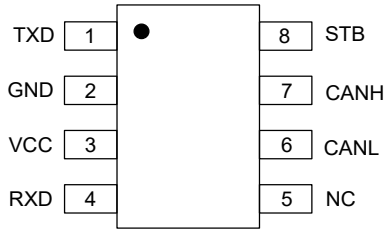


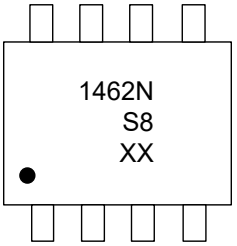
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SOP8



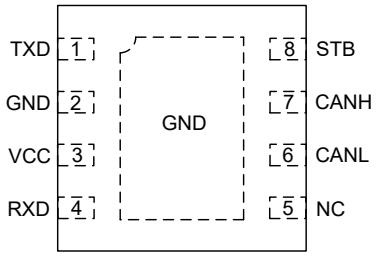


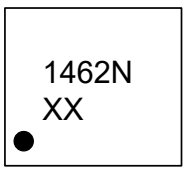
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SOP8





XX: Week Code
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DFN8 3.0×3.0

5 Pin Configuration and Function (continued)

Table 5-1. Pin Functions

Pin No.	Symbol	Description
1	TXD	Transmit data input
2	GND	Ground (Note 1)
3	V_{CC}	Supply voltage
4	RXD	Receive data output; reads out data from the bus lines
5	V_{IO}	Supply voltage for I/O level adapter
	NC	Not connected in UMCAN1462NS8 and UMCAN1462NDA versions
6	CANL	Low-level CAN bus line
7	CANH	High-level CAN bus line
8	STB	Standby mode control input

Note 1: DFN8 package die supply ground is connected to both the GND pin and the exposed center pad. The GND pin must be soldered to board ground. For enhanced thermal and electrical performance, it is recommended that the exposed center pad also be soldered to board ground.

6 Specifications

6.1 Absolute Maximum Ratings (Note 1, 2, 3)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	Bus supply voltage		-0.3		+7	V
V_{IO}	Supply voltage I/O level shifter		-0.3		+7	V
V_{BUS}	Voltage range on CANH, CANL		-40		+40	V
V_{DIF}	Voltage range between CANH and CANL		-40		+40	V
V_I	Voltage range on STB	Note 4	-0.3		V_{IO}+0.3	V
	Voltage range on TXD	Note 4	-0.3		V_{IO}+0.3	V
V_O	Voltage range on RXD	Note 4	-0.3		V_{IO}+0.3	V
V_{trt}	Transient voltage on CANH, CANL pins (Note 5)	pulse 1	-100			V
		pulse 2a			+75	V
		pulse 3a	-150			V
		pulse 3b			+100	V
V_{ESD}	Human-body model (HBM), per ANSI/ESDA/ JEDEC JS-001	All pins		±8		kV
	Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002	All pins		±2		kV
	Contact discharge, per IEC 61000-4-2	Bus pins		±10		kV
I_{LU}	Latch up, per JEDEC JESD78	Class II		200		mA
T_{VJ}	Virtual junction temperature		-40		150	℃
T_{STG}	Storage temperature		-55		150	℃

Note 1: Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
Note 2: All voltage values, except differential I/O bus voltages, are with respect to ground terminal.
Note 3: V_{IO} = V_{CC} in non-VIO product variants.
Note 4: Maximum voltage should never exceed 7 V.
Note 5: Verified by an external test house according to IEC TS 62228, Section 4.2.4; parameters for standard pulses defined in ISO 7637.

6.2 Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	Bus supply voltage		4.5		5.5	V
V_{IO}	Supply voltage I/O level shifter		2.9		5.5	V
T_A	Operating ambient temperature		-40		125	℃

6.3 Electrical Characteristics (Note 1)

T_J = -40℃ to +150℃; V_{CC} = 4.5V to 5.5V; V_{IO} = 2.9V to 5.5V; R_L = 60Ω; C_L = 100pF unless otherwise specified; All voltages are defined with respect to ground; positive currents flow into the IC.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supply; pin VCC						
$V_{UVD(STB)}$	Standby undervoltage detection voltage on pin VCC		3.5	4	4.3	V
$V_{UVD(SWOFF)VCC}$	Switch-off undervoltage detection voltage on pin VCC	Variants without VIO	2.4	2.6	2.8	V
I_{CC}	Supply current	Variants without a VIO pin; STB = V_{CC}; TXD = V_{CC}		10	17.5	uA
		Variants with a VIO pin; STB = V_{IO}; TXD = V_{IO}		0.1	1	uA
		STB = 0 V; TXD = V_{IO}		1.6	5	mA
		STB = 0 V; TXD = 0	20	45	60	mA
		STB = 0 V; TXD = 0 V; short circuit on bus lines; -3V < (CANH=CANL) < 18V		80	110	mA
I/O level adapter supply; pin VIO						
$V_{UVD(SWOFF)VIO}$	Switch-off undervoltage detection voltage on pin VIO	Variants with a VIO pin	2.4	2.6	2.8	V
I_{IO}	supply current on pin VIO	STB = V_{IO}; TXD = V_{IO}		8	16.5	uA
		STB = 0 V; TXD = V_{IO}	5	10	30	uA
		STB = 0 V; TXD = 0V		110	300	uA
Standby mode control input; pin STB						
V_{IH}	High-level input voltage		0.7V_{IO}			V
V_{IL}	Low-level input voltage				0.3V_{IO}	V
I_{IH}	High-level input current	STB = V_{IO}	-1		1	uA
I_{IL}	Low-level input current	STB = 0 V	-15		-1	uA

6.3 Electrical Characteristics (Note 1) (continued)

T_J = -40℃ to +150℃; V_{CC} = 4.5V to 5.5V; V_{IO} = 2.9V to 5.5V; R_L = 60Ω; C_L = 100pF unless otherwise specified; All voltages are defined with respect to ground; positive currents flow into the IC.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
CAN transmit data input; pin TXD						
V_{IH}	High-level input voltage		$0.7V_{IO}$			V
V_{IL}	Low-level input voltage				$0.3V_{IO}$	V
I_{IH}	High-level input current	TXD = V_{IO}	-5		5	uA
I_{IL}	Low-level input current	TXD = 0 V	-270	-100	-60	uA
C_I	Input capacitance			5	10	pF
CAN receive data output; pin RXD						
I_{OH}	High-level output current	RXD = V_{IO} - 0.4 V	-9	-1.5		mA
I_{OL}	Low-level output current	RXD = 0.4V		1.5	12	mA
Driver						
$V_{O(DOM)}$	Dominant output voltage	STB = 0 V; TXD = 0 V; $t < t_{TO(DOM)TXD}$; 50 Ω ≤ R_L ≤ 65 Ω; pin CANH	2.75	3.5	4.5	V
		STB = 0 V; TXD = 0 V; $t < t_{TO(DOM)TXD}$; 50 Ω ≤ R_L ≤ 65 Ω; pin CANL	0.5	1.5	2.25	V
$V_{OD(DOM)}$	Dominant differential output voltage	STB = 0 V; TXD = 0 V; $t < t_{TO(DOM)TXD}$; 50 Ω ≤ R_L ≤ 65 Ω	1.5		3	V
		STB = 0 V; TXD = 0 V; $t < t_{TO(DOM)TXD}$; 45 Ω ≤ R_L ≤ 70 Ω	1.4		3.3	V
		STB = 0 V; TXD = 0 V; $t < t_{TO(DOM)TXD}$; R_L = 2240 Ω	1.5		5	V

6.3 Electrical Characteristics (Note 1) (continued)

T_J = -40℃ to +150℃; V_{CC} = 4.5V to 5.5V; V_{IO} = 2.9V to 5.5V; R_L = 60Ω; C_L = 100pF unless otherwise specified; All voltages are defined with respect to ground; positive currents flow into the IC.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{SYM(DOM)}$	Dominant output voltage symmetry, V_{CC} - CANH – CANL	STB = 0 V; TXD = 0 V; $t < t_{TO(DOM)TXD}$; R_L = 60 Ω	-400		400	mV
$V_{O(REC)}$	Recessive output voltage	STB = 0 V; TXD = V_{IO}; R_L = open	2	0.5V_{CC}	3	V
$V_{OD(REC)}$	Recessive differential output voltage	STB = 0 V; TXD = V_{IO}; R_L = open	-50		50	mV
$V_{O(STB)}$	Bus output voltage, Standby Mode	STB = V_{IO}; TXD = V_{IO}; R_L = open	-100		100	mV
$V_{OD(STB)}$	Bus differential output voltage, Standby Mode	STB = V_{IO}; TXD = V_{IO}; R_L = open	-200		200	mV
$V_{SYM(TX)}$	Transmitter output voltage symmetry, (CANH + CANL)/V_{CC}	STB = 0 V; TXD = 250 kHz, 1 MHz, 2.5MHz; R_L = 60 Ω; C_{SPLIT} = 4.7 nF	0.9V_{CC}		1.1V_{CC}	V
$V_{CM(STEP)}$	Common mode voltage step	See figure 7-4	-150		150	mV
$V_{CM(PP)}$	Peak-to-peak common mode voltage	See figure 7-4	-400		400	mV
$I_{OS(DOM)}$	Dominant short-circuit output current	STB = 0 V; TXD = 0 V; VCC = 5 V; CANH = -15 V to 40 V; CANL = open	-100	-70		mA
		STB = 0 V; TXD = 0 V VCC = 5 V; CANL = -15 V to 40 V; CANH = open		70	100	mA
$I_{OS(REC)}$	Recessive short-circuit output current	STB = 0 V; TXD = V_{IO}; -27 V ≤ CANH = CANL ≤ 32 V	-5		5	mA
Receiver						
V_{TH}	Differential receiver threshold voltage, Normal mode	STB = 0 V; -15 V ≤ CANH, CANL ≤ 15 V	0.5		0.9	V
$V_{ID(DOM)}$	Receiver dominant voltage, Normal mode	STB = 0 V; -15 V ≤ CANH, CANL ≤ 15 V	0.9		9	V
$V_{ID(REC)}$	Receiver recessive voltage, Normal mode	STB = 0 V; -15 V ≤ CANH, CANL ≤ 15 V	-4		0.5	V
V_{HYS}	Differential receiver hysteresis voltage, Normal mode	STB = 0 V; -15 V ≤ CANH, CANL ≤ 15 V	50		300	mV

6.3 Electrical Characteristics (Note 1) (continued)

T_J = -40℃ to +150℃; V_{CC} = 4.5V to 5.5V; V_{IO} = 2.9V to 5.5V; R_L = 60Ω; C_L = 100pF unless otherwise specified; All voltages are defined with respect to ground; positive currents flow into the IC.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{TH(STB)}$	Differential receiver threshold voltage, Standby mode	STB = V_{IO}; -15 V ≤ CANH, CANL ≤ 15 V	0.4		1.15	V
$V_{ID(DOM)STB}$	Receiver dominant voltage, Standby mode	STB = V_{IO}; -15 V ≤ CANH, CANL ≤ 15 V	1.15		9	V
$V_{ID(REC)STB}$	Receiver recessive voltage, Standby mode	STB = V_{IO}; -15 V ≤ CANH, CANL ≤ 15 V	-4		0.4	V
$I_{LKG(PD)}$	Unpowered Leakage current	V_{CC} = V_{IO} = 0 V or shorted to GND via 47 kΩ; CANH = CANL = 5 V	-5		18	uA
R_I	Input resistance	STB = 0 V; TXD = V_{IO}; -2 V ≤ CANH, CANL ≤ 7 V	15	30	40	kΩ
ΔR_I	Input resistance deviation, [1 – ($R_{IN(CANH)}$ / $R_{IN(CANL)}$)] × 100 %	STB = 0 V; TXD = V_{IO}; -2 V ≤ CANH, CANL ≤ 7 V	-3		3	%
R_{ID}	Differential input resistance	STB = 0 V; TXD = V_{IO}; -2 V ≤ CANH, CANL ≤ 7 V	30	60	80	kΩ
C_{IN}	Common-mode input capacitance to ground				20	pF
C_{ID}	Differential input capacitance				10	pF
Thermal Protection						
$T_{J(SD)}$	Thermal shutdown threshold	Temperature rising		185		℃

Note 1: V_{IO} = V_{CC} in non-VIO product variants.

6.4 Switching Characteristics (Note 7)

T_J = -40℃ to +150℃; V_{CC} = 4.5V to 5.5V; V_{IO} = 2.9V to 5.5V; R_L = 60Ω; C_L = 100pF unless otherwise specified; all voltages are defined with respect to ground.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
CAN timing characteristics according to ISO 11898-2:2024; see Figure 7-1 and Figure 7-3						
$t_{D(TXDL-RXDL)}$	Delay time from TXD LOW to RXD LOW	STB = 0 V			255	ns
$t_{D(TXDH-RXDH)}$	Delay time from TXD HIGH to RXD HIGH	STB = 0 V			255	ns
CAN timing characteristics according to ISO 11898-2:2024; V_{CC} = 4.75 V to 5.25 V; see Figure 7-1, Figure 7-3 and Figure 7-5						
$t_{D(TXD-BUSDOM)}$	Delay time from TXD to bus dominant	STB = 0 V			80	ns
$t_{D(TXD-BUSREC)}$	Delay time from TXD to bus recessive	STB = 0 V			80	ns
$t_{D(BUSDOM -RXD)}$	Delay time from bus dominant to RXD	STB = 0 V			110	ns
$t_{D(BUSREC -RXD)}$	Delay time from bus recessive to RXD	STB = 0 V			110	ns
$t_{D(TXDL-RXDL)}$	Delay time from TXD LOW to RXD LOW	STB = 0 V			190	ns
$t_{D(TXDH-RXDH)}$	Delay time from TXD HIGH to RXD HIGH	STB = 0 V			190	ns
$t_{SIC(TXD)BASE}$	delay time from TXD to bus active recessive end	STB = 0 V (Note 1)	355		480	ns
CAN FD timing characteristics according to ISO 11898-2:2024 parameter set C ($t_{BIT(TXD)}$ ≥125 ns, up to 8 Mbit/s; V_{CC} = 4.75 V to 5.25 V; see Figure 7-1 and Figure 7-3) (Note 2)						
$\Delta t_{BIT(BUS)}$	Transmitted recessive bit width deviation	$\Delta t_{BIT(BUS)}= t_{BIT(BUS)}- t_{BIT(TXD)}$	-10		10	ns
Δt_{REC}	Receiver timing symmetry	$\Delta t_{REC}= t_{BIT(RXD)}- t_{BIT(BUS)}$	-20		15	ns
$\Delta t_{BIT(RXD)}$	Received recessive bit width deviation	$\Delta t_{REC}= t_{BIT(RXD)}- t_{BIT(TXD)}$	-30		20	ns

6.4 Switching Characteristics (Note 7) (continued)

T_J = -40℃ to +150℃; V_{CC} = 4.5V to 5.5V; V_{IO} = 2.9V to 5.5V; R_L = 60Ω; C_L = 100pF unless otherwise specified; all voltages are defined with respect to ground.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
CAN FD timing characteristics according to ISO 11898-2:2016 and ISO 11898-2:2024; V_{CC} = 4.75 V to 5.25 V; see Figure 7-1 and Figure 7-3						
$t_{BIT(BUS)}$	Transmitted recessive bit width	2 Mbit/s ($t_{BIT(TXD)}$ = 500 ns)	490		510	ns
		5 Mbit/s ($t_{BIT(TXD)}$ = 200 ns)	190		210	ns
$t_{BIT(RXD)}$	Bit time on pin RXD (Note 1)	2 Mbit/s ($t_{BIT(TXD)}$ = 500 ns)	470		520	ns
		5 Mbit/s ($t_{BIT(TXD)}$ = 200 ns)	170		220	ns
$\Delta t_{BIT(BUS)}$	Transmitted recessive bit width deviation	2 Mbit/s ($t_{BIT(TXD)}$ = 500 ns) $\Delta t_{BIT(BUS)} = t_{BIT(BUS)} - t_{BIT(TXD)}$	-65		30	ns
Δt_{REC}	Receiver timing symmetry	2 Mbit/s ($t_{BIT(TXD)}$ = 500 ns) $\Delta t_{REC} = t_{BIT(RXD)} - t_{BIT(BUS)}$	-65		40	ns
$\Delta t_{BIT(RXD)}$	Received recessive bit width deviation	2 Mbit/s ($t_{BIT(TXD)}$ = 500 ns) $\Delta t_{REC} = t_{BIT(RXD)} - t_{BIT(TXD)}$	-100		50	ns
$\Delta t_{BIT(BUS)}$	Transmitted recessive bit width deviation	5 Mbit/s ($t_{BIT(TXD)}$ = 200 ns) $\Delta t_{BIT(BUS)} = t_{BIT(BUS)} - t_{BIT(TXD)}$	-45		10	ns
Δt_{REC}	Receiver timing symmetry	5 Mbit/s ($t_{BIT(TXD)}$ = 200 ns) $\Delta t_{REC} = t_{BIT(RXD)} - t_{BIT(BUS)}$	-45		15	ns
$\Delta t_{BIT(RXD)}$	Received recessive bit width deviation	5 Mbit/s ($t_{BIT(TXD)}$ = 200 ns) $\Delta t_{REC} = t_{BIT(RXD)} - t_{BIT(TXD)}$	-80		20	ns
Dominant time-out time; pin TXD (Note 3)						
$t_{TO(DOM)TXD}$	TXD dominant time-out time	STB = 0 V; TXD = 0V	0.8		9	ms
Bus wake-up times; pins CANH and CANL; see Figure 9-3 (Note 3, 4)						
$t_{WK(BUSDOM)}$	Bus dominant wake-up time	STB = V_{IO}	0.5		1.8	us
$t_{WK(BUSREC)}$	Bus recessive wake-up time	STB = V_{IO}	0.5		1.8	us
$t_{TO(WK)BUS}$	Bus wake-up time-out time	STB = V_{IO}	0.8		9	ms
$t_{FLTR(WK)BUS}$	Bus wake-up filter time	STB = V_{IO}			1.8	us
Mode transitions						
$t_{D(STB-NRM)}$	Mode change time, from standby to normal				50	us
$t_{STARTUP(RXD)}$	RXD start-up time	After wake-up detected (Note 5)	4		20	us

6.4 Switching Characteristics (Note 7) (continued)

T_J = -40℃ to +150℃; V_{CC} = 4.5V to 5.5V; V_{IO} = 2.9V to 5.5V; R_L = 60Ω; C_L = 100pF unless otherwise specified; all voltages are defined with respect to ground.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
IO filter; pin STB (Note 6)						
$t_{FLTR(IO)}$	IO filter time	on pin STB	1		5	us

Note 1: Not tested in production; guaranteed by design.
Note 2: Compliance with parameter set C requirements implies compliance for parameter sets A ($t_{BIT(TXD)}$) ≥ 500 ns, up to 2 Mbit/s) and B ($t_{BIT(TXD)}$) ≥ 200 ns, up to 5 Mbit/s).
Note 3: Time-out occurs between the min and max values. Time-out is guaranteed not to occur below the min value; time-out is guaranteed to occur above the max value.
Note 4: A dominant/recessive phase shorter than the min value is guaranteed not be seen as a dominant/recessive bit; a dominant/recessive phase longer than the max value is guaranteed to be seen as a dominant/recessive bit.
Note 5: When a wake-up is detected, RXD start-up time is between the min and max values. RXD cannot be relied on below the min value; RXD can be relied on above the max value; see Figure 9-3.
Note 6: Pulses shorter than the min value are guaranteed to be filtered out; pulses longer than the max value are guaranteed to be processed.
Note 7: V_{IO} = V_{CC} in non-VIO product variants.

7 Parameter Measurement Information

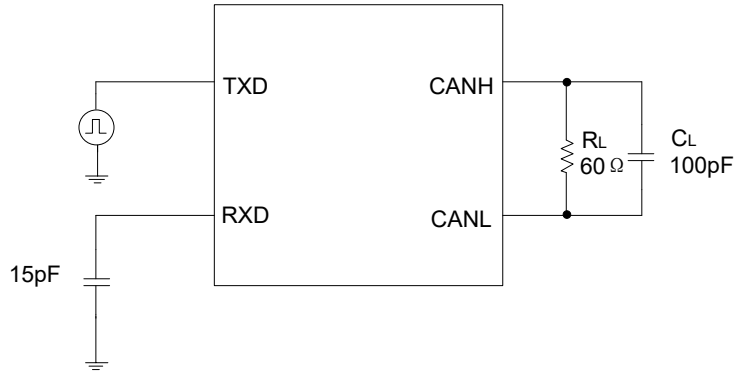


Figure 7-1. CAN transceiver timing test circuit

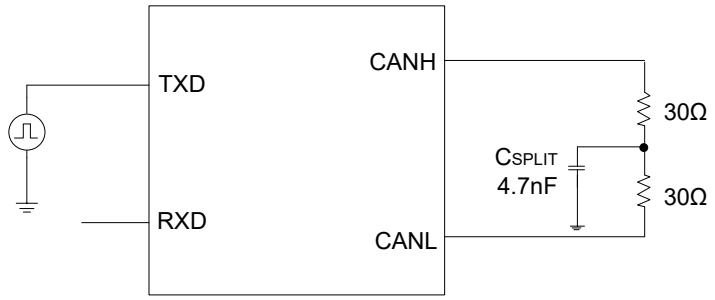


Figure 7-2. Test circuit for measuring transceiver transmitter driver symmetry

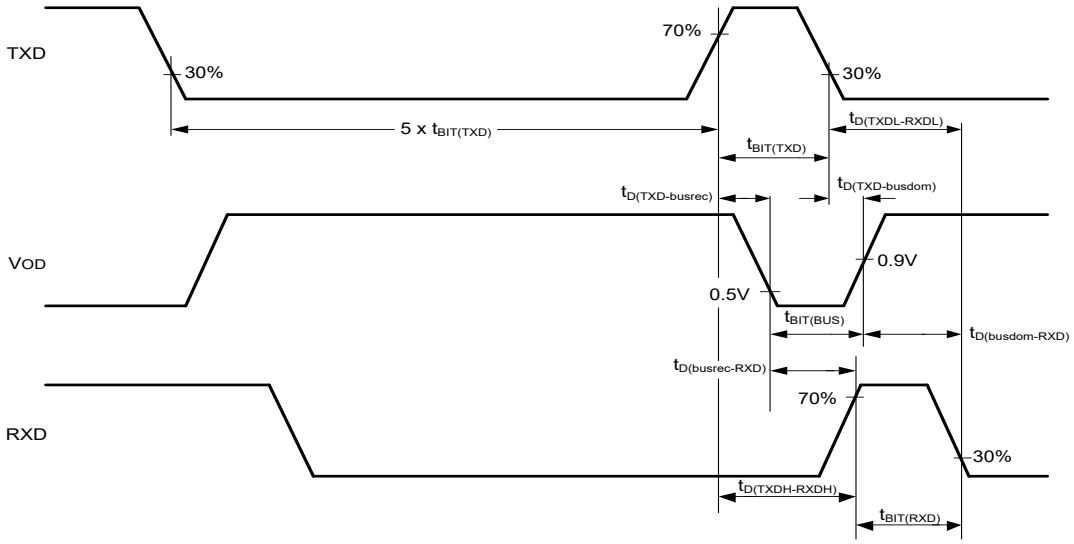


Figure 7-3. CAN transceiver timing diagram according to ISO 11898-2:2024

7 Parameter Measurement Information (continued)

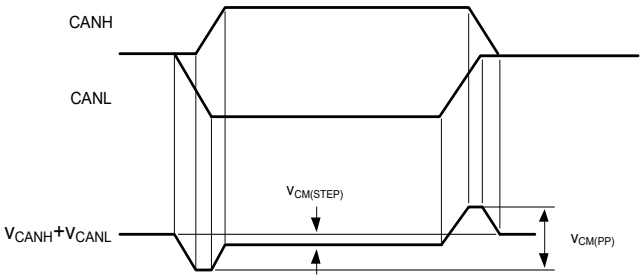


Figure 7-4. CAN bus common-mode voltage according to SAE 1939-14

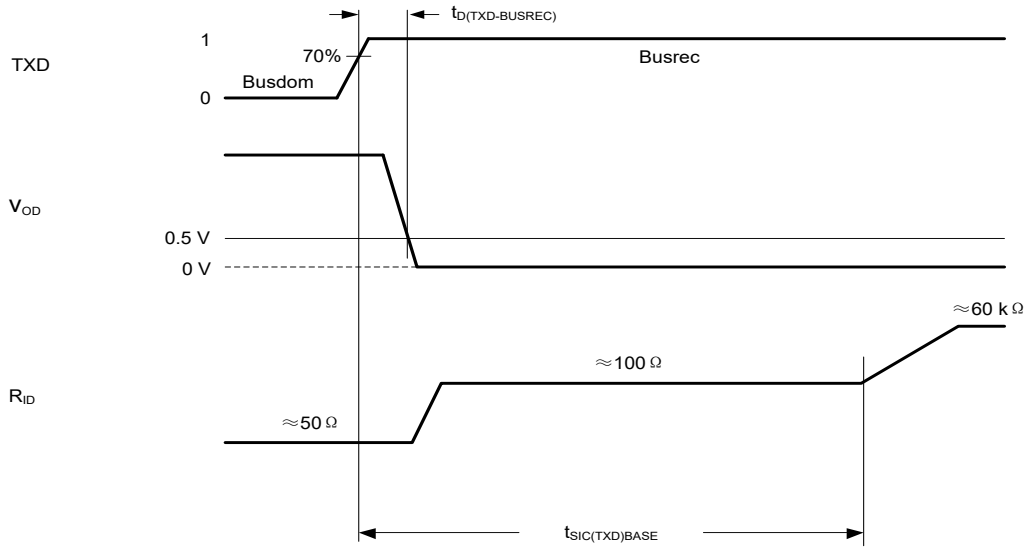


Figure 7-5. UMCAN1462 transmitter impedance and timing diagram for dominant-to-passive recessive transition

8 Block diagram

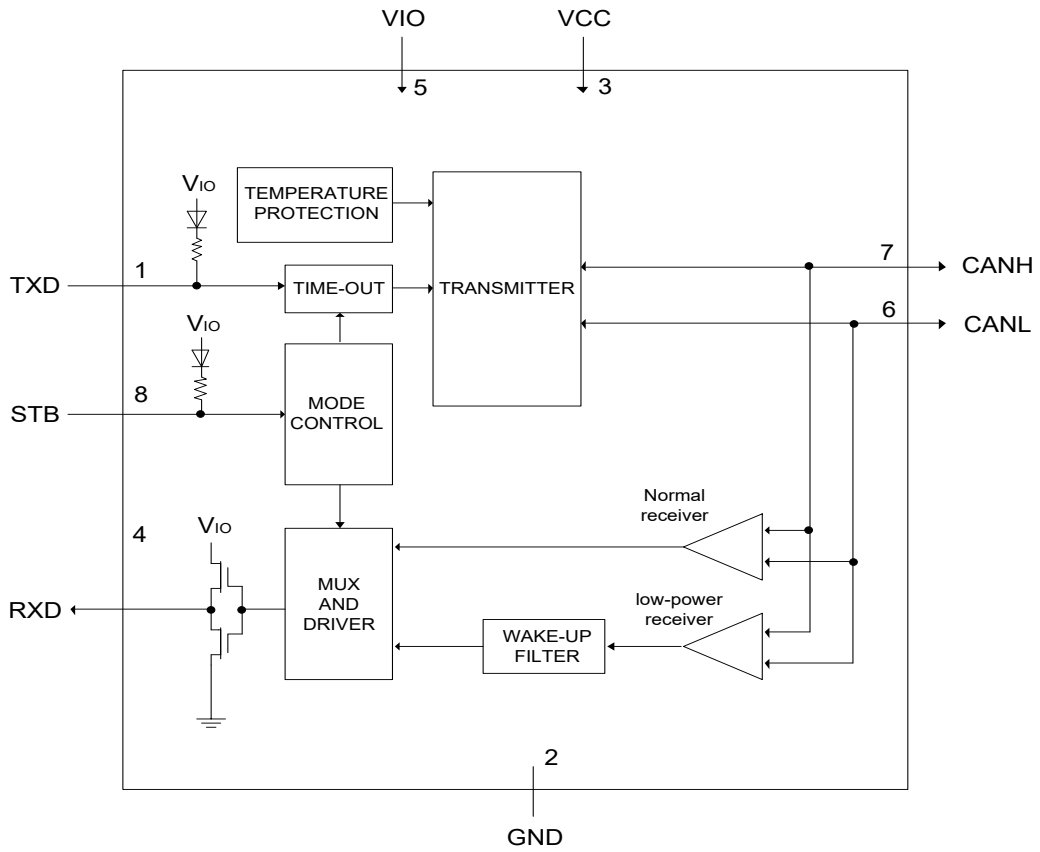


Figure 8-1. Block diagram

9 Detailed Description

9.1 Operating modes

The UMCAN1462 supports three operating modes, Normal, Standby and Off. The operating mode is selected via pin STB. See Table for a description of the operating modes under normal supply conditions.

Mode	Inputs		Outputs	
	Pin STB	Pin TXD	CAN driver	Pin RXD
Normal	LOW	LOW	dominant	LOW
		HIGH	recessive	LOW when bus dominant
				HIGH when bus recessive
Standby	HIGH	X (Note 1)	biased to ground	follows BUS when wake-up detected
				HIGH when no wake-up detected
Off	X	X	High-Z state	High-Z state

Note 1: “X” = don’t care.

9.1 Operating modes (continued)

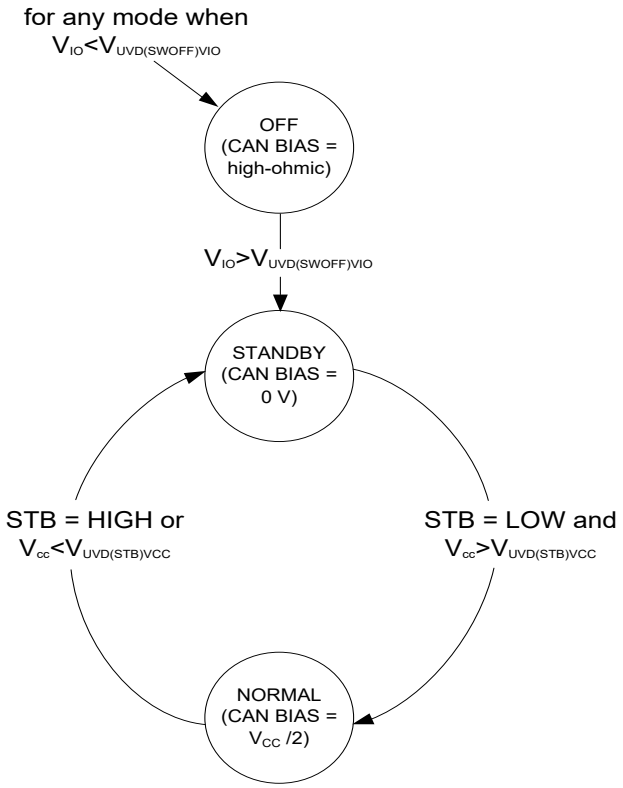


Figure 9-1. UMCAN1462 state diagram

9.1.1 Normal mode

A LOW level on pin STB selects Normal mode, provided the supply voltage on pin V_{CC} is above the standby undervoltage detection threshold, $V_{UVD(STB)(VCC)}$
In this mode, the transceiver can transmit and receive data via the bus lines CANH and CANL (see Figure 8-1 for the block diagram). The differential receiver converts the
analog data on the bus lines into digital data on pin RXD. The slopes of the output signals on the bus lines are controlled internally and are optimized in a way that guarantees the lowest possible EME. In order to support high bit rates, especially in CAN FD systems, the Signal Improvement function largely eliminates topology-related reflections and impedance mismatches. In recessive state, the output voltage on the bus pins is $V_{CC}/2$.

9.1.2 Standby mode

A HIGH level on pin STB selects Standby mode. In Standby mode, the transceiver is not able to transmit or correctly receive data via the bus lines. The transmitter and Normal mode receiver blocks are switched off to reduce supply current, and only a low-power differential receiver monitors the bus lines for activity. In Standby mode, the bus lines are biased to ground to minimize system supply current. The low-power receiver is supplied from VIO and can detect CAN bus activity even if VIO is the only available supply voltage. Pin RXD follows the bus after a wake-up request has been detected. A transition to Normal mode is triggered when STB is forced LOW.

9.1.3 Off mode

The UMCAN1462 switches to Off mode from any mode when the supply voltage(on pin V_{IO} in UMCAN1462V and V_{CC} in UMCAN1462N) falls below the switch-off undervoltage threshold ($V_{UVD(SWOFF)VIO}$ or $V_{UVD(SWOFF)VCC}$). This is the default mode when the supply is first connected. In Off mode, the CAN pins and pin RXD are in a High-Z state.

9.1.4 Operating modes and gap-free operation

Gap-free operation guarantees defined behavior at all voltage levels. Supply voltage-to-operating mode mapping is detailed in Figure 9-2 and in the state diagrams (Figure 9-1).

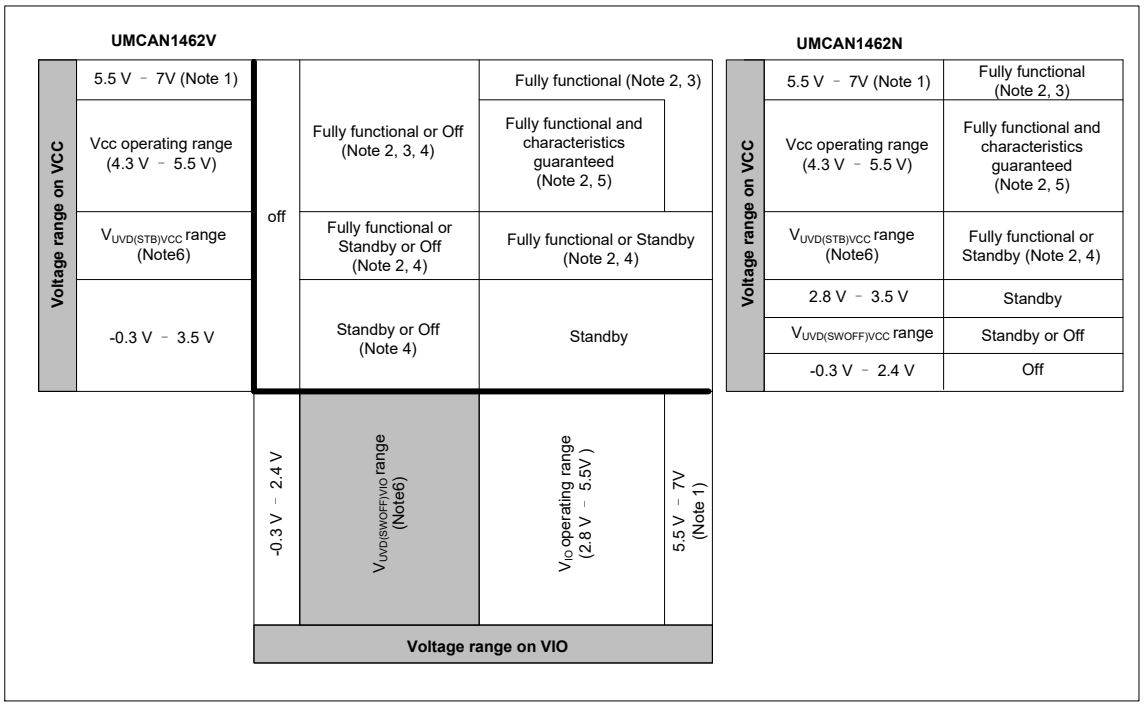


Figure 9-2. Supply voltage ranges and gap-free operation

Note 1: Maximum voltage should never exceed 7 V.
Note 2: Target transceiver functionality as described in this datasheet is applicable.
Note 3: Prolonged operation of the device outside the operating range may impact reliability over lifetime. Returning to the operating range, datasheet characteristics are guaranteed provided the AMR has not been exceeded.
Note 4: For a given value of V_{IO}, a specific device will be in a single defined state determined by its undervoltage detection thresholds ($V_{UVD(STB)VCC}$ and $V_{UVD(SWOFF)VIO}$). The actual thresholds can vary between devices (within the ranges specified in this datasheet). To guarantee the device will be in a specific state, V_{IO} and V_{CC} must be either above the maximum or below the minimum thresholds specified for these undervoltage detection ranges.
Note 5: Datasheet characteristics are guaranteed within the V_{CC} and V_{IO} operating ranges. Exceptions are described in the Static and Dynamic characteristics tables.
Note 6: The following applies to UMCAN1462:

- If both V_{CC} and V_{IO} are above the undervoltage threshold, the device is fully functional.
- If V_{CC} is below and V_{IO} above the undervoltage threshold, the device is in Standby mode.
- If V_{IO} is below the undervoltage threshold, the device is in Off mode, regardless of V_{CC}.

9.2 Remote wake-up (via the CAN bus)

The UMCAN1462 wakes up from Standby mode when a dedicated wake-up pattern (specified in ISO 11898-2:2024) is detected on the bus. This filtering helps avoid spurious wake-up events. A spurious wake-up sequence could be triggered by, for example, a dominant clamped bus or by dominant phases due to noise or spikes on the bus.
The wake-up pattern consists of:

- a dominant phase of at least $t_{WK(BUSDOM)}$ followed by
- a recessive phase of at least $t_{WK(BUSREC)}$ followed by
- a dominant phase of at least $t_{WK(BUSDOM)}$

Dominant or recessive bits between the above mentioned phases that are shorter than $t_{WK(BUSDOM)}$ and $t_{WK(BUSREC)}$ respectively are ignored.
The complete dominant-recessive-dominant pattern must be received within $t_{TO(WK)BUS}$ to be recognized as a valid wake-up pattern. Otherwise, the internal wake-up logic is reset. The complete wake-up pattern will then need to be retransmitted to trigger a wake-up event. Pin RXD remains HIGH until the wake-up event has been triggered.
After a wake-up sequence has been detected, the UMCAN1462 will remain in Standby mode with the bus signals reflected on RXD after $t_{STARTUP(RXD)}$. Note that dominant or recessive phases lasting less than $t_{FLTR(WK)BUS}$ will not be detected by the low-power differential receiver and will not be reflected on RXD in Standby mode.
A wake-up event is not flagged on RXD if any of the following events occurs while a valid wake-up pattern is being received:

- The device switches to Normal mode
- The complete wake-up pattern was not received within $t_{TO(WK)BUS}$
- A V_{CC} or V_{IO} undervoltage is detected ($V_{CC} < V_{UVD(SWOFF)(VCC)}$ or $V_{IO} < V_{UVD(SWOFF)VIO}$);

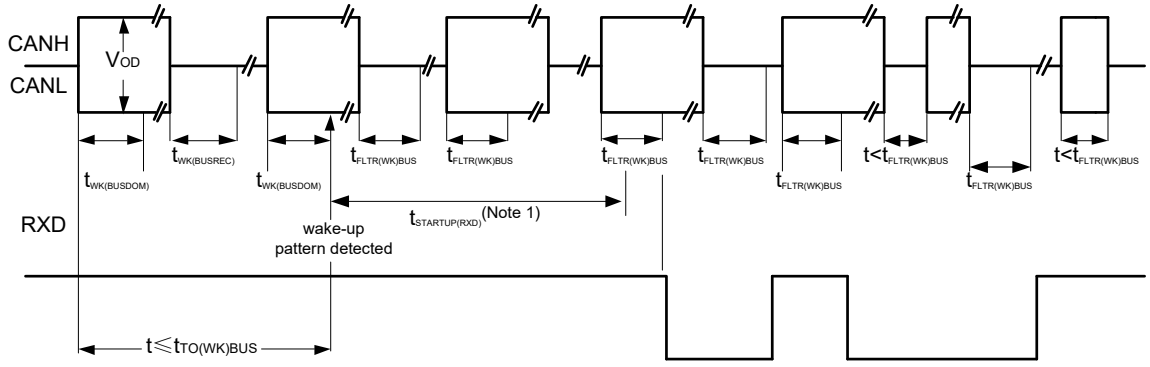


Figure 9-3. Wake-up timing

Note 1: During $t_{STARTUP(RXD)}$, the low-power receiver is on but pin RXD is not active (i.e. HIGH/recessive). The first dominant pulse of width ≥ $t_{FLTR(WK)BUS}$ that ends after $t_{STARTUP(RXD)}$ will trigger RXD to go LOW/dominant.

9.3 Fail-safe features

9.3.1 TXD dominant time-out function

A TXD dominant time-out' timer is started when pin TXD is set LOW. If the LOW state on this pin persists for longer than $t_{TO(DOM)TXD}$, the transmitter is disabled, releasing the bus lines to recessive state. This function prevents a hardware and/or software application failure from driving the bus lines to a permanent dominant state (blocking all network communications). The TXD dominant time-out timer is reset when pin TXD is set HIGH.

9.3.2 Internal biasing of TXD and STB input pins

Pins TXD and STB have internal pull-ups to V_{CC}/V_{IO} to ensure a safe, defined state in case one or both of these pins are left floating. Pull-up currents flow in these pins in all states; both pins should be held HIGH in Standby mode to minimize supply current.

9.3.3 Undervoltage detection on pins V_{CC} and V_{IO}

If V_{CC} drops below the standby undervoltage detection level, $V_{UVD(STB)VCC}$, the transceiver switches to Standby mode. The logic state of pin STB is ignored until V_{CC} has recovered.
In versions with a V_{IO} pin, if V_{IO} drops below the switch-off undervoltage detection level ($V_{UVD(SWOFF)VIO}$), the transceiver switches off and disengages from the bus (High-Z) until V_{IO} has recovered.
In versions without a V_{IO} pin, if V_{CC} drops below the switch-off undervoltage detection level ($V_{UVD(SWOFF)VCC}$), the transceiver switches off and disengages from the bus (High-Z) until V_{CC} has recovered.

9.3.4 Over temperature protection

The output drivers are protected against overtemperature conditions. If the virtual junction temperature exceeds the shutdown junction temperature, $T_{J(SD)}$, both output drivers are disabled. When the virtual junction temperature drops below $T_{J(SD)}$ again, the output drivers recover once TXD has been reset to HIGH. Including the TXD condition prevents output driver oscillation due to small variations in temperature.

9.3.5 I/O levels

Pin V_{IO} should be connected to the microcontroller supply voltage. This will adjust the signal levels of pins TXD, RXD and STB to the I/O levels of the microcontroller. Pin V_{IO} also provides the internal supply voltage for the low-power differential receiver. For applications running in low-power mode, this allows the bus lines to be monitored for activity even if there is no supply voltage on pin V_{CC}.
All I/O levels are related to V_{CC} in the UMCAN1462N and are, therefore, compatible with 5 V microcontrollers
For both the UMCAN1462V and UMCAN1462N, spurious signals from the microcontroller on pin STB are filtered out with a filter time of $t_{FLTR(IO)}$.

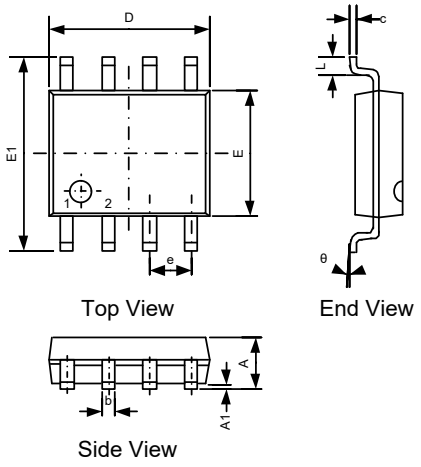
9.4 Signal Improvement

Signal improvement is an additional capability added to CAN FD transceiver that enhances the maximum data rate achievable in complex star topologies by minimizing signal ringing. Signal ringing is the result of reflections caused by impedance mismatch at various points in a CAN network due to the nodes that act as stubs.
Recessive-to-dominant signal edge is usually clean as it is strongly driven by the transmitter. Transmitter output impedance of CAN transceiver is ≈ 50 Ω and matches to the network characteristic impedance. For a regular CAN FD transceiver, dominant-to-recessive edge is when the driver output impedance goes to ≈ 60 kΩ and signal reflected back experiences impedance mismatch which causes ringing. UMCAN1462 resolves this issue by TX-based Signal improvement capability (SIC). The device continues to drive the bus recessive until $t_{SIC(TXD)BASE}$ so that reflections die down and recessive bit is clean at sampling point. In the active recessive phase, transmitter output impedance is low (≈ 100 Ω). After this phase is over and device goes to passive recessive phase, driver output impedance goes to high-Z. This phenomenon is explained at Figure 7-5.

10 Package Information

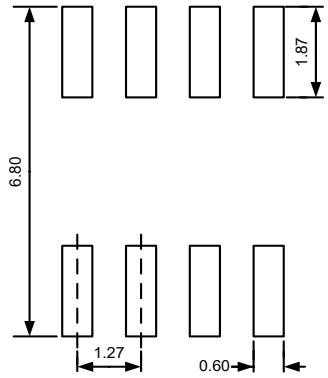
SOP8

Outline Drawing



Symbol	DIMENSIONS					
	MILLIMETERS			INCHES		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.75	-	-	0.069
A1	0.00	-	0.25	0.000	-	0.010
b	0.30	-	0.51	0.012	-	0.020
c	0.15	-	0.25	0.006	-	0.010
D	4.70	4.90	5.10	0.185	0.193	0.200
E	3.70	3.90	4.10	0.148	0.154	0.164
E1	5.80	-	6.25	0.228	-	0.250
e	1.27BSC			0.050 BSC		
L	0.40	-	1.27	0.016	-	0.050
θ	0°	-	8°	0°	-	8°

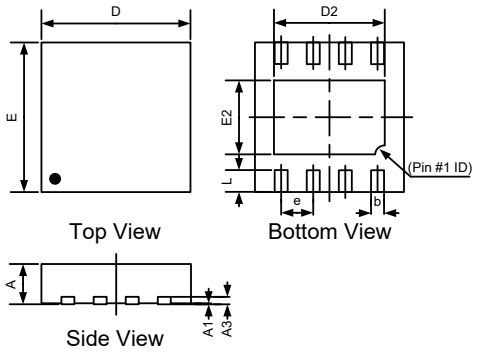
Land Pattern



NOTES:
1. Unit: mm;
2. General tolerance ±0.05mm unless otherwise specified;
3. The layout is just for reference.

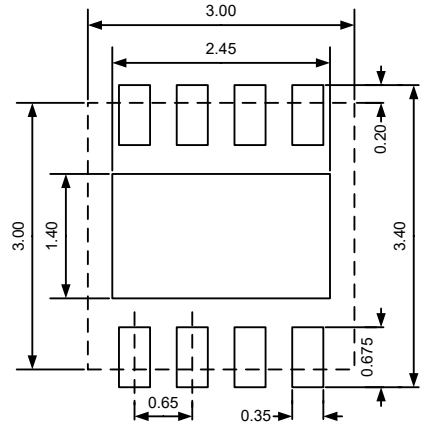
DFN8 3.0×3.0

Outline Drawing



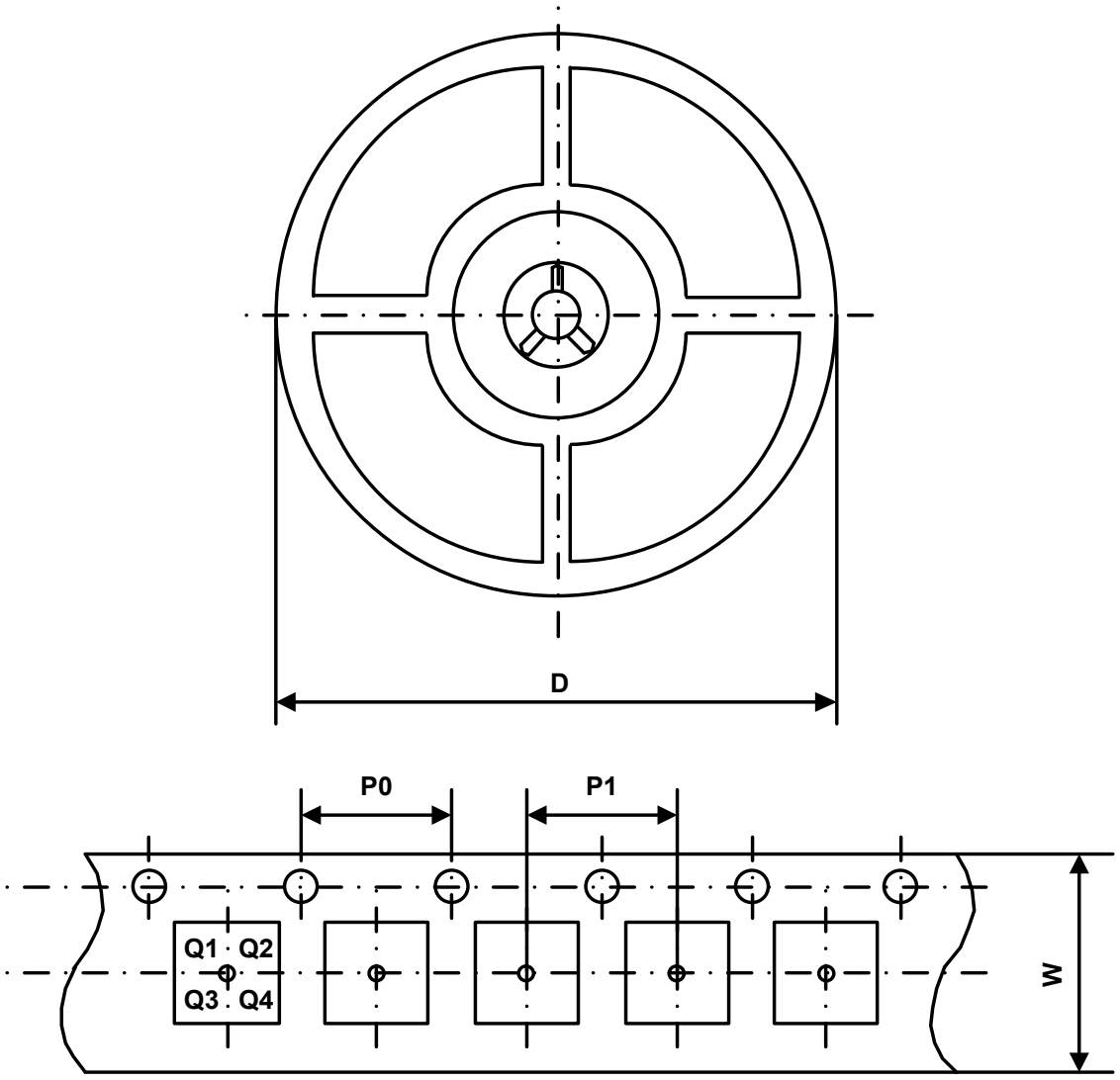
DIMENSIONS						
Symbol	MILLIMETERS			INCHES		
	Min	Typ	Max	Min	Typ	Max
A	0.57	-	0.80	0.022	-	0.031
A1	0.00	-	0.05	0.000	-	0.002
A3	0.20REF			0.008REF		
b	0.20	-	0.35	0.008	-	0.014
D	2.90	3.00	3.10	0.114	0.118	0.122
D2	2.15	-	2.60	0.085	-	0.104
E	2.90	3.00	3.10	0.114	0.118	0.122
E2	1.40	-	1.75	0.055	-	0.069
e	0.65BSC			0.026BSC		
L	0.30	-	0.60	0.012	-	0.024

Land Pattern



NOTES:
1. Unit: mm;
2. General tolerance ±0.05mm unless otherwise specified;
3. The layout is just for reference.

11 Packing Information



Part Number	Package Type	Carrier Width (W)	Pitch (P0)	Pitch (P1)	Reel Size (D)	PIN 1 Quadrant
UMCAN1462VS8	SOP8	12 mm	4 mm	8 mm	330 mm	Q1
UMCAN1462VDA	DFN8 3.0×3.0	12 mm	4 mm	8 mm	330 mm	Q1
UMCAN1462NS8	SOP8	12 mm	4 mm	8 mm	330 mm	Q1
UMCAN1462NDA	DFN8 3.0×3.0	12 mm	4 mm	8 mm	330 mm	Q1

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